

Abstract

Power module having at least two substrates and a method for producing it

The invention relates to a power module 3 and a method for producing it. The power module 3 has a first substrate 1 having power semiconductor chips 4, and a second substrate 2 populated with signal semiconductor chips 5. The substrates 1 and 2 are oriented parallel one above the other, their placement sides 7 and 8 being arranged facing one another, and the second substrate 2, with the aid of bonding wires 9 bent in hingelike fashion, being held at a defined distance  $d$  from the first substrate 1 and being mechanically fixed in a plastic housing 18 and electrically connected.

[Figure 1]